



## Final Product Change Notification

202003003F01

**Issue Date:** 20-Apr-2020

**Effective Date:** 19-Jul-2020

Dear *Tracy Hoglin*,

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

**This notice is NXP Company Proprietary.**



# QUALITY

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |  |   |   |

**MPC5607B/5606B 176LQFP  
Assembly Site Expansion  
from ASE-CL (Chung Li,  
Taiwan) to NXP-ATKL (Kuala  
Lumpur, Malaysia)**

### Description of Change

NXP Semiconductors announces the Assembly site expansion for MPC5607B and MPC5606B (176LQFP) associated with this notification from the current ASE, Chung Li, Taiwan (ASE-CL) assembly facility to NXP-ATKL, Kuala Lumpur, Malaysia (NXP-ATKL) assembly facility.

Assembly site expansion was successfully qualified adhering to NXP specifications.  
Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-03, SEM-PA-11 and SEM-PA-18.

Please see attached files for additional details.

### Reason for Change

Qualification of NXP-ATKL, Kuala Lumpur, Malaysia is required for manufacturing flexibility and customer supply assurance.

### Identification of Affected Products

There is no change to orderable part number.  
Change in package trace code is explained under the 'Remarks' section below.

## Product Availability

### Sample Information

Samples are available upon request  
Samples are available upon request

Sample part numbers information is available in the "Communication Package" file attached.

### Production

Planned first shipment 09-Oct-2020

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

### Disposition of Old Products

Assembly site expansion. No depletion of Inventory required.

## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 20-May-2020.

## Remarks

The assembly site, among other information, is reflected in the package trace code.  
The format for the NXP standard trace code: AWLYYYWW is the following:  
A=Assembly Site, WL=Wafer Lot, YY=Year, WW=Work Week.

The current assembly site marking for site 1 (ASECL) is A = X  
The marking for proposed assembly site 2 (ATKL) is A = Q

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Bharat Lal Rotion Lal  
**Position** Product Engineer  
**e-mail address** bharatlal.rotionlal@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.  
Customer Focus, Passion to Win.

NXP Quality Management Team.

## About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
SPC5606BF1VLU6	935321526557	SPC5606BF1VLU6	BOLERO 1.5M CUT 2.2	SOT506-2	LQFP176	RFS	General Purp & Int Solutions
SPC5607BK0MLU6	935318032557	SPC5607BK0MLU6	32BIT 1.5M FLASH 96K RAM	SOT506-2	LQFP176	RFS	General Purp & Int Solutions
SPC5607BF1VLU6R	935311254528	SPC5607BF1VLU6R	32BIT 1.5M FLASH 96K RAM	SOT506-2	LQFP176	RFS	General Purp & Int Solutions
SPC5607BF1VLU6	935311254557	SPC5607BF1VLU6	32BIT 1.5M FLASH 96K RAM	SOT506-2	LQFP176	RFS	General Purp & Int Solutions